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Date: August 16, 2002

Joseph R. Keating

PATENT
36856.345

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

~~Applicant:~~ Masaya WAJIMA et al.

Art Unit: 2834

~~Serial No.:~~ 09/656,106

~~Filed:~~ September 6, 2000

Examiner: J. Gonzalez

~~Title:~~ CHIP ELECTRONIC COMPONENT
AND MOUNTING STRUCTURE OF THE
SAME

TECHNOLOGY CENTER 2800
AUG 29 2002

RECEIVED

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated May 16, 2002, please amend the above-identified patent application as follows:

IN THE CLAIMS:

Please replace claims 1, 9, 13 and 14 with the following claims:

1. A chip electronic component comprising:
a body of the chip electronic component having outer peripheral surfaces
including an upper surface, a lower surface and a pair of side surfaces;
an electronic component element having electrodes and defining part of said
body of the chip electronic component; and